

NPN medium power transistor

BC868

FEATURES

- High current (max. 1 A)
- Low voltage (max. 20 V).

APPLICATIONS

- General purpose switching and amplification
- Power applications such as audio output stages.

DESCRIPTION

NPN medium power transistor in a SOT89 plastic package. PNP complement: BC869.

MARKING

TYPE NUMBER	MARKING CODE
BC868	CAC
BC868-10	CBC
BC868-16	CCC
BC868-25	CDC

PINNING

PIN	DESCRIPTION
1	emitter
2	collector
3	base

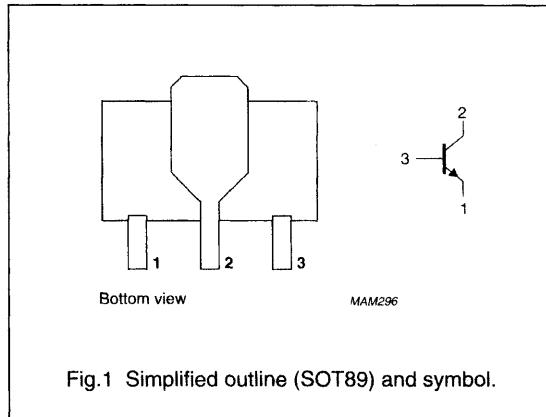


Fig.1 Simplified outline (SOT89) and symbol.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	-	32	V
V_{CEO}	collector-emitter voltage	open base	-	20	V
I_{CM}	peak collector current		-	2	A
P_{tot}	total power dissipation	$T_{amb} \leq 25^\circ\text{C}$	-	1.4	W
h_{FE}	DC current gain	$I_C = 500 \text{ mA}; V_{CE} = 1 \text{ V}$	85	375	
f_T	transition frequency	$I_C = 10 \text{ mA}; V_{CE} = 5 \text{ V}; f = 100 \text{ MHz}$	40	-	MHz

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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	-	32	V
V_{CEO}	collector-emitter voltage	open base	-	20	V
V_{EBO}	emitter-base voltage	open collector	-	5	V
I_C	collector current (DC)		-	1	A
I_{CM}	peak collector current		-	2	A
I_{BM}	peak base current		-	200	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25^\circ\text{C}$; note 1	-	1.4	W
T_{stg}	storage temperature		-65	+150	$^\circ\text{C}$
T_j	junction temperature		-	150	$^\circ\text{C}$
T_{amb}	operating ambient temperature		-65	+150	$^\circ\text{C}$

Note

1. Device mounted on a printed-circuit board, single sided copper, tinplated, mounting pad for collector 1 cm².
For other mounting conditions, see "Thermal considerations for SOT89 in the General part of handbook SC04".

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th j-a}$	thermal resistance from junction to ambient	note 1	89	K/W
$R_{th j-s}$	thermal resistance from junction to soldering point		8	K/W

Note

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CHARACTERISTICS

 $T_j = 25^\circ\text{C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_{CBO}	collector cut-off current	$I_E = 0; V_{CB} = 25\text{ V}$	—	—	100	nA
		$I_E = 0; V_{CB} = 25\text{ V}; T_j = 150^\circ\text{C}$	—	—	10	μA
I_{EBO}	emitter cut-off current	$I_C = 0; V_{EB} = 5\text{ V}$	—	—	100	nA
h_{FE}	DC current gain	$I_C = 5\text{ mA}; V_{CE} = 10\text{ V}$	50	—	—	
h_{FE}	DC current gain	$V_{CE} = 1\text{ V}$; see Fig.2				
		$I_C = 500\text{ mA}$	85	—	375	
		$I_C = 1\text{ A}$	60	—	—	
h_{FE}	DC current gain BC868-10 BC868-16 BC868-25	$I_C = 500\text{ mA}; V_{CE} = 1\text{ V}$; see Fig.2				
			—	—	160	
			100	—	250	
			160	—	—	
V_{CEsat}	collector-emitter saturation voltage	$I_C = 1\text{ A}; I_B = 100\text{ mA}$	—	—	500	mV
V_{BE}	base-emitter voltage	$I_C = 5\text{ mA}; V_{CE} = 10\text{ V}$	—	620	—	mV
		$I_C = 1\text{ A}; V_{CE} = 1\text{ V}$	—	—	1	V
f_T	transition frequency	$I_C = 10\text{ mA}; V_{CE} = 5\text{ V}; f = 100\text{ MHz}$	40	—	—	MHz
h_{FE1} h_{FE2}	DC current gain ratio of the complementary pairs	$ I_C = 0.5\text{ A}; V_{CE} = 1\text{ V}$	—	—	1.6	

